Fabrication and characterization of eutectic gold–silicon (Au–Si) nanowires

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\textbf{Abstract}

Hypoeutectic, eutectic and hypereutectic gold–silicon (Au–Si) alloys were synthesized using vacuum smelting. When Au and Si were smelted in a vacuum chamber near 1100 °C, Si(g), Si\(_2\)(g), Si\(_3\)(g), SiO\(_2\)(g), Au(g), SiO\(_2\)(s) and Au\(_2\)O\(_3\)(s) were formed rapidly; the quantities of Au and Si lost were estimated from thermodynamic formulas. The nano- and microstructures of the Au–Si eutectic compound were characterized with a SEM and a TEM, which showed a discontinuous phase of Si dispersed and mounted within a matrix phase of Au. Cracks that formed about the Au–Si interface made the Au–Si eutectic brittle. From an Au–Si alloy of superior quality as a bulk material, eutectic nanowires of average diameter 60 nm were fabricated after the alloy was melted and injected into an anodic aluminum-oxide (AAO) template.

\section{Introduction}

Gold is a conductive noble metal, and silicon is a base material for the semiconductor industry. Gold is commonly used in semiconductor products. For example, an Au–Si eutectic alloy is used for microchip packing and interconnection in micro-electro-mechanical systems (MEMS). As an Au–Si eutectic has a useful field-emission property, it serves for panels or displays; for example, a 70-nm Au–Si eutectic tip has an initiating field only 10 V\textmu m\(^{-1}\) (Wan et al., 2004). Furthermore, when an Au–Si eutectic is set on a 10-\textmu m tip, a large field current 300 \textmu A is obtainable on the tip (Zhironov et al., 1996). Although such an Au–Si alloy has excellent electronic characteristics, the mechanical properties of such an Au–Si alloy are generally detrimental to product quality. According to Komatsu and Kiritani (2003), an Au–Si eutectic becomes brittle upon subjecting to the cold-rolling process. Gold is a ductile material, but a small proportion of brittle silicon in gold makes the alloy become brittle.

According to the Au–Si binary phase diagram (Massalski, 1987) shown in Fig. 1, the melting points of Au and Si are 1064 °C and 1414 °C, respectively, whereas the eutectic point has a melting point only 363 °C. No compound formation of any composition occurs in an Au–Si alloy, but three alloy phases – hypoeutectic, eutectic and hypereutectic – appear in the Au–Si diagram. When the temperature is greater than that of the liquid line, mixed Au and Si in a liquid phase appear; hypoeutectic and hypereutectic phases appear when the temperature decreases along hypoeutectic and hypereutectic lines.

The fabrication of nanowires by non-lithographic methods such as ion deposition has been reported (Komatsu and Kiritani, 2003; Massalski, 1987; Wang et al., 2001; Zhang et al., 2000; Nielsch et al., 2001). Problems are associated with ion deposition when high current density is used. These problems arise from the ion implantation of Au particles, which makes the surface inhomogeneous. In this study, non-lithographic methods are applied to fabricate Au–Si nanowires.
Fig. 1 – Au–Si phase diagram: hypoeutectic composition of point a (2.3 mass% Si–Au), eutectic composition of point b (2.8 mass% Si–Au), and hypereutectic composition of point c (4.0 mass% Si–Au).

Fig. 2 – Schematic diagram of Au–Si alloys made with vacuum smelting: (a) ratio (mass%) of Au and Si in the vacuum tube and (b) after heating, Au–Si alloys formed in the tube.

Fig. 3 – OM images of Au–Si alloys: (a) Si–Au of hypoeutectic (2.3 mass%), (b) Si–Au of eutectic (2.8 mass%), and (c) Si–Au of hypereutectic (4.0 mass%).

Table 1 – Thermodynamic equilibrium reactions in the Au–Si–O system

<table>
<thead>
<tr>
<th>Reaction</th>
<th>Equations</th>
<th>log K</th>
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<tbody>
<tr>
<td>$\text{Si(g)} \rightarrow \text{Si}_2\text{g}$</td>
<td>$\log P_{\text{Si}_2\text{g}} = \log K$</td>
<td>7.694 – (23447.16/T)</td>
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<tr>
<td>$2\text{Si(g)} \rightarrow \text{Si}_2\text{g}$</td>
<td>$\log P_{\text{Si}_2\text{g}} = \log K$</td>
<td>3.505 – (26942.52/T)</td>
</tr>
<tr>
<td>$3\text{Si(g)} \rightarrow \text{Si}_3\text{g}$</td>
<td>$\log P_{\text{Si}_3\text{g}} = \log K$</td>
<td>10.465 – (32920.81/T)</td>
</tr>
<tr>
<td>$\text{Si}_3\text{g} + O_2(g) \rightarrow \text{SiO}_2(g)$</td>
<td>$\log P_{\text{SiO}<em>2\text{g}} = \log K + \log P</em>{O_2\text{g}}$</td>
<td>0.0672 + (16043.28/T)</td>
</tr>
<tr>
<td>$\text{Si}_3\text{g} + O_2(g) \rightarrow \text{SiO}_2(g)$</td>
<td>$\log P_{\text{Si}_2\text{O}_3\text{g}} = -\log K$</td>
<td>9.252 + (47410.44/T)</td>
</tr>
<tr>
<td>$\text{Au}(g) \rightarrow \text{Au}_{2}\text{O}_3(g)$</td>
<td>$\log P_{\text{Au}_{2}\text{O}_3\text{g}} = \log K$</td>
<td>6.6484 – (19083.24/T)</td>
</tr>
<tr>
<td>$2\text{Au}(g) + (3/2)O_2(g) \rightarrow \text{Au}_2\text{O}_3(g)$</td>
<td>$\log P_{O_2\text{g}} = (-2/3) \log K$</td>
<td>13.94 + (88.5/T)</td>
</tr>
</tbody>
</table>
deposition, such as a large cost of instruments and a small yield, and the quality of nanowires is jeopardized by the presence of a catalyst required for the ion deposition. In contrast, metal casting is a method well established in metallurgy. The experience gained from this traditional casting combined with emerging nanotechnological methods are prospectively useful in minimizing the cost of nanomaterial fabrication, improving the efficiency of fabrication, and decreasing the complication of the fabrication. For these reasons we fabricated hypoeutectic, eutectic and hypereutectic Au–Si alloys using vacuum smelting; we subsequently formed Au–Si eutectic nanowires by vacuum die-casting using an anodic aluminum-oxide (AAO) thin film as a template.

2. Experiments

Au–Si alloys with three compositions—hypoeutectic (2.3 mass% Si–Au, sample a), eutectic (2.8 mass% Si–Au, sample b), and hypereutectic (4.0 mass% Si–Au, sample c), were fabricated using vacuum smelting. Highly pure (99.99%) gold foil and single-crystal silicon wafers were used for the Au–Si alloys. Samples a–c were placed in quartz tubes that were then evacuated ($P \sim 3 \times 10^{-6}$ Torr) with a turbo molecular pump, purged with argon, and sealed in an oxyacetylene flame. The sealed tubes were heated at 1100 °C for 1 h, with occasional agitation to achieve a homogeneous melt. A schematic diagram is presented in Fig. 2. The melt was then cooled in air to form Au–Si bulk alloys. The metallurgical microstructure and composition of the alloys were examined with an optical microscope (Olympus BX51), a scanning electron microscope

Fig. 5 – Vapor pressures of Au and Si as a function of temperature.

Fig. 6 – Equilibrium partial pressures of oxygen in (a) Au/Au$_2$O$_3$, (b) Si/SiO$_2$(g), and (c) Si/SiO$_2$(s).
Fig. 7 – SEM images of (a) Au–Si eutectic, (b) zoomed image, and (c) EDS diagram.

Fig. 8 – SEM images of AAO: (a) top view and (b) side view.

(352x414 to 579x773)
Au lost during vacuum smelting is greater than that of Si. In our experiment, the extra Au (0.2 mass%) was added over the eutectic point for Au–Si eutectic formation.

A compound with a ductile matrix and a brittle precipitation structure is typically ductile in bulk. For example, a eutectoid structure of pearlite forms with a ductile Fe matrix and a discontinuous brittle cementite (Fe₃C) precipitation phase (Callister, 1994); a eutectic structure of Sn–Bi alloy forms with a ductile Sn matrix and a discontinuous brittle Bi precipitation phase. The Pb–Bi eutectic is likewise ductile in bulk, but an Au–Si eutectic alloy is a brittle material. Fig. 7 shows SEM images of the Au–Si eutectic microstructure. In the image of Fig. 7(a) at small magnification, a discontinuous phase of Si disperses into the matrix phase of Au. In the image presented in (b) at large magnification, Si is mounted inside Au, and cracks have formed about the Au–Si interface; this cracking makes the Au–Si eutectic brittle. In Au–Si phase diagram, Au and Si cannot form alloy in the Au–Si melt mixture. When the melt mixture was solidified, the solid phases of Au and Si were formed separately. Because the thermal condense coefficients of Au and Si are different (Au: 14.2 × 10⁻⁶ K⁻¹, Si: 2.6 × 10⁻⁶ K⁻¹) (Dean, 1992), the Au–Si mixture cracks easily, as shown in (b).

Fig. 8 shows SEM images of AAO with ordered nanochannels at the packing density 4 × 10¹² cm⁻². The pores have diameter 60 nm and length 57 μm. An AAO template of satisfactory quality is required for fabrication of Au–Si nanowires. Fig. 9(a) (top view) and (b) (side view) show SEM images of Au–Si eutectic nanowires produced on vacuum die-casting with an AAO template; (c) shows Au–Si nanowires after the template was dissolved in phosphoric acid (20 vol.%). The diameter and length of the nanowires depend on the AAO size; in this case, the Au–Si eutectic nanowires have diameter ~60 nm and length ~57 μm. To investigate the detailed morphology of individual nanowires that were deposited on a Cu grid after the AAO template was thoroughly dissolved, we employed a TEM: two TEM images of a randomly selected nanowire appear in Fig. 10; the black particles are Si according to EDS.
4. Conclusion

Using vacuum smelting method Au–Si hypoeutectic, eutectic, and hypereutectic alloys were fabricated. Because more Au than Si is lost during this smelting, the extra Au was added to the alloy to achieve an Au–Si eutectic alloy with the correct stoichiometry. The melting points and microstructures of alloys were measured with a differential scanning calorimeter and an optical microscope; these results correlated satisfactorily with the Au–Si phase diagram. Au–Si eutectic nanowires of diameter $\sim 60$ nm have been successfully made with die-casting and AAO as a template. SEM and TEM images show the morphology of the nanostructure of Au–Si eutectic nanowires with Si nanoparticles dispersed in the Au matrix.

Acknowledgements

National Science Council of Republic of China (contract 95–2113–M–009–027) and the MOE–ATU program provided financial support.

REFERENCES
